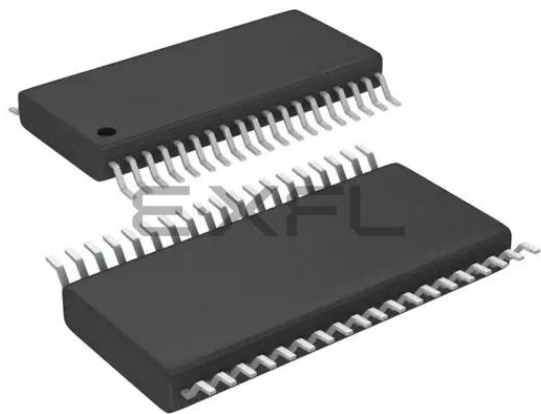




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Details

Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc866l-2fra-be

XC866 Data Sheet**Revision History: 2007-10****V1.2**

Previous Version: V 0.1, 2005-01

V1.0, 2006-02

V1.1, 2006-12

Page	Subjects (major changes since last revision)
3	Device summary table is updated for Flash 4-Kb and ROM variants.
13	Footnote is added to MBC pin; description of V_{DDP} pin is updated.
25	Section on bit protection scheme and access type of register bit field PASSWD.PASS are updated.
26	Access type of PAGE bits of all module page registers are corrected to rwh.
29	Access type of Px_DIR register bits are corrected to rwh
38	New bullet point on Flash delivery state is added to the feature list.
88	Digital power supply voltage are differentiated for 5V and 3.3V variants.
89	New parameters on XTAL1 hysteresis and Voltage on GPIO pins during V_{DDP} power-off condition are added.
104	Figure on Power-on reset timing is updated.

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2.2 Logic Symbol

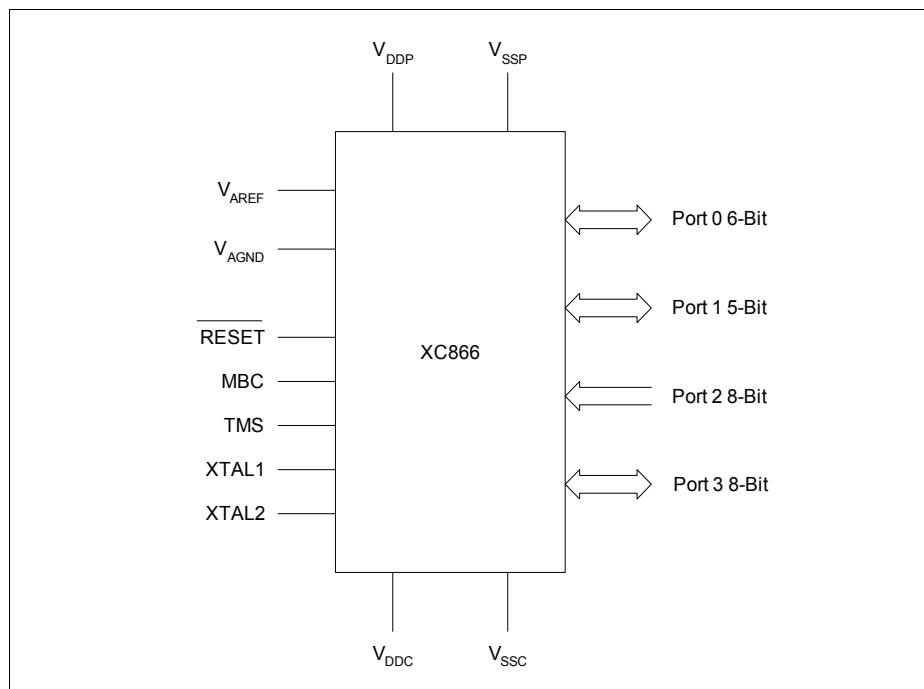


Figure 3 XC866 Logic Symbol

2.3 Pin Configuration

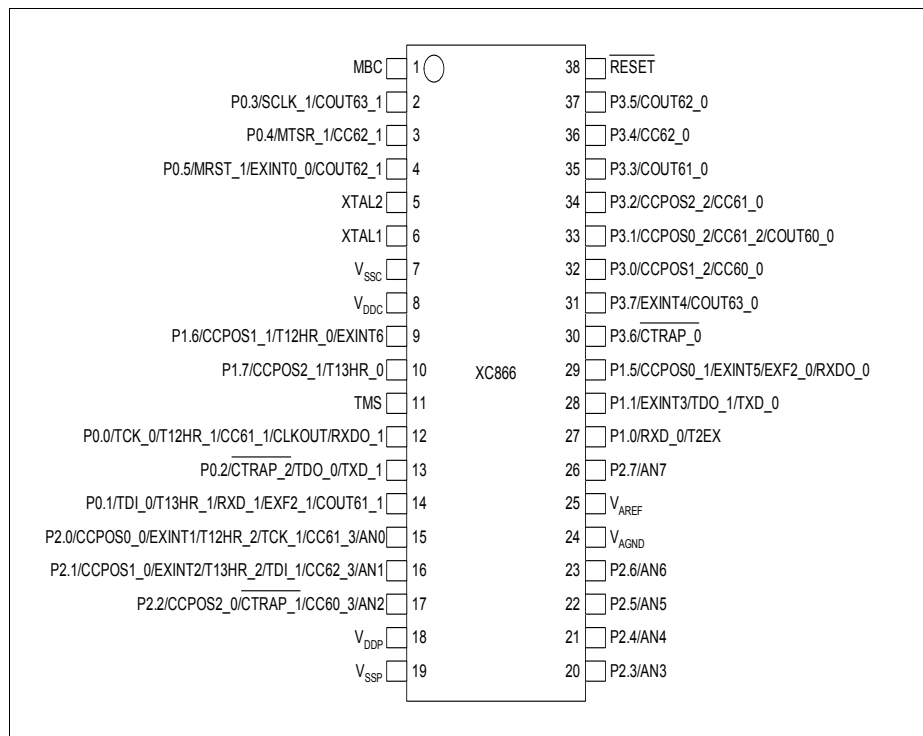


Figure 4 XC866 Pin Configuration, PG-TSSOP-38 Package (top view)

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P3		I		Port 3 Port 3 is a bidirectional general purpose I/O port. It can be used as alternate functions for the CCU6.
P3.0	32		Hi-Z	CCPOS1_2 CCU6 Hall Input 1 CC60_0 Input/Output of Capture/Compare channel 0
P3.1	33		Hi-Z	CCPOS0_2 CCU6 Hall Input 0 CC61_2 Input/Output of Capture/Compare channel 1 COUT60_0 Output of Capture/Compare channel 0
P3.2	34		Hi-Z	CCPOS2_2 CCU6 Hall Input 2 CC61_0 Input/Output of Capture/Compare channel 1
P3.3	35		Hi-Z	COUT61_0 Output of Capture/Compare channel 1
P3.4	36		Hi-Z	CC62_0 Input/Output of Capture/Compare channel 2
P3.5	37		Hi-Z	COUT62_0 Output of Capture/Compare channel 2
P3.6	30		PD	<u>CTRAP_0</u> CCU6 Trap Input
P3.7	31		Hi-Z	EXINT4 External Interrupt Input 4 COUT63_0 Output of Capture/Compare channel 3

Functional Description

Figure 7 illustrates the memory address spaces of the XC866-4RR device.

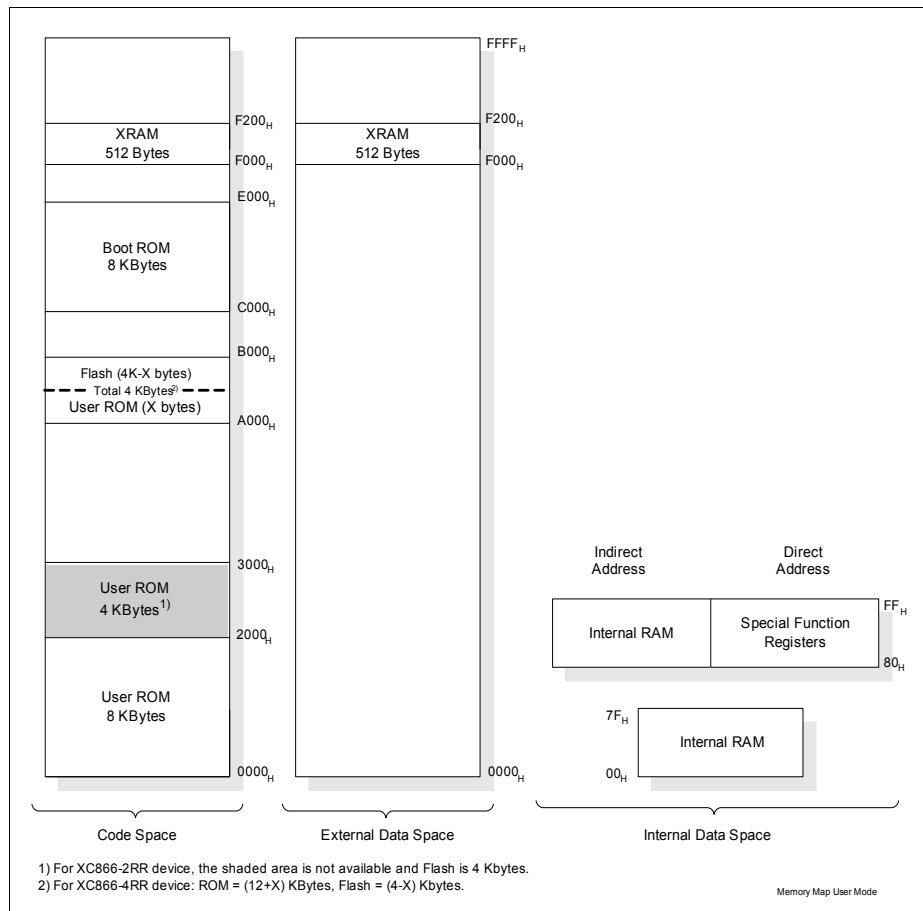


Figure 7 Memory Map of XC866 ROM Devices

3.2.4 XC866 Register Overview

The SFRs of the XC866 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in [Table 7](#) to [Table 15](#), with the addresses of the bitaddressable SFRs appearing in bold typeface.

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Table 7 CPU Register Overview

Addr	Register Name		Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1											
81 _H	SP Stack Pointer Register	Reset: 07 _H	Bit Field	SP							
			Type	rw							
82 _H	DPL Data Pointer Register Low	Reset: 00 _H	Bit Field	DPL7	DPL6	DPL5	DPL4	DPL3	DPL2	DPL1	DPL0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
83 _H	DPH Data Pointer Register High	Reset: 00 _H	Bit Field	DPH7	DPH6	DPH5	DPH4	DPH3	DPH2	DPH1	DPH0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
87 _H	PCON Power Control Register	Reset: 00 _H	Bit Field	SMOD	0			GF1	GF0	0	IDLE
			Type	rw	r			rw	rw	r	rw
88 _H	TCON Timer Control Register	Reset: 00 _H	Bit Field	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
			Type	rwh	rw	rwh	rw	rwh	rw	rwh	rw
89 _H	TMOD Timer Mode Register	Reset: 00 _H	Bit Field	GATE1	0	T1M		GATE0	0	T0M	
			Type	rw	r	rw		rw	r	rw	
8A _H	TL0 Timer 0 Register Low	Reset: 00 _H	Bit Field	VAL							
			Type	rwh							
8B _H	TL1 Timer 1 Register Low	Reset: 00 _H	Bit Field	VAL							
			Type	rwh							
8C _H	TH0 Timer 0 Register High	Reset: 00 _H	Bit Field	VAL							
			Type	rwh							
8D _H	TH1 Timer 1 Register High	Reset: 00 _H	Bit Field	VAL							
			Type	rwh							
98 _H	SCON Serial Channel Control Register	Reset: 00 _H	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
			Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
99 _H	SBUF Serial Data Buffer Register	Reset: 00 _H	Bit Field	VAL							
			Type	rwh							
A2 _H	EO Extended Operation Register	Reset: 00 _H	Bit Field	0			TRAP EN	0			DPSEL 0
			Type	r			rw	r			rw
A8 _H	IE0 Interrupt Enable Register 0	Reset: 00 _H	Bit Field	EA	0	ET2	ES	ET1	EX1	ET0	EX0
			Type	rw	r	rw	rw	rw	rw	rw	rw
B8 _H	IP Interrupt Priority Register	Reset: 00 _H	Bit Field	0		PT2	PS	PT1	PX1	PT0	PX0
			Type	r		rw	rw	rw	rw	rw	rw
B9 _H	IPH Interrupt Priority Register High	Reset: 00 _H	Bit Field	0		PT2H	PSH	PT1H	PX1H	PT0H	PX0H
			Type	r		rw	rw	rw	rw	rw	rw
D0 _H	PSW Program Status Word Register	Reset: 00 _H	Bit Field	CY	AC	F0	RS1	RS0	OV	F1	P
			Type	rw	rwh	rwh	rw	rw	rwh	rwh	rw
E0 _H	ACC Accumulator Register	Reset: 00 _H	Bit Field	ACC7	ACC6	ACC5	ACC4	ACC3	ACC2	ACC1	ACC0
			Type	rw	rw	rw	rw	rw	rw	rw	rw
E8 _H	IE1 Interrupt Enable Register 1	Reset: 00 _H	Bit Field	ECCIP 3	ECCIP 2	ECCIP 1	ECCIP 0	EXM	EX2	ESSC	EADC
			Type	rw	rw	rw	rw	rw	rw	rw	rw

Functional Description

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CA _H	ADC_RESR0L Result Register 0 Low Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CB _H	ADC_RESR0H Result Register 0 High Reset: 00 _H	Bit Field	RESULT[9:2]							
		Type	rh							
CC _H	ADC_RESR1L Result Register 1 Low Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CD _H	ADC_RESR1H Result Register 1 High Reset: 00 _H	Bit Field	RESULT[9:2]							
		Type	rh							
CE _H	ADC_RESR2L Result Register 2 Low Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
CF _H	ADC_RESR2H Result Register 2 High Reset: 00 _H	Bit Field	RESULT[9:2]							
		Type	rh							
D2 _H	ADC_RESR3L Result Register 3 Low Reset: 00 _H	Bit Field	RESULT[1:0]		0	VF	DRC	CHNR		
		Type	rh		r	rh	rh	rh		
D3 _H	ADC_RESR3H Result Register 3 High Reset: 00 _H	Bit Field	RESULT[9:2]							
		Type	rh							
RMAP = 0, Page 3										
CA _H	ADC_RESRA0L Result Register 0, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CB _H	ADC_RESRA0H Result Register 0, View A High Reset: 00 _H	Bit Field	RESULT[10:3]							
		Type	rh							
CC _H	ADC_RESRA1L Result Register 1, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CD _H	ADC_RESRA1H Result Register 1, View A High Reset: 00 _H	Bit Field	RESULT[10:3]							
		Type	rh							
CE _H	ADC_RESRA2L Result Register 2, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CF _H	ADC_RESRA2H Result Register 2, View A High Reset: 00 _H	Bit Field	RESULT[10:3]							
		Type	rh							
D2 _H	ADC_RESRA3L Result Register 3, View A Low Reset: 00 _H	Bit Field	RESULT[2:0]			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
D3 _H	ADC_RESRA3H Result Register 3, View A High Reset: 00 _H	Bit Field	RESULT[10:3]							
		Type	rh							
RMAP = 0, Page 4										
CA _H	ADC_RCR0 Result Control Register 0 Reset: 00 _H	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CB _H	ADC_RCR1 Result Control Register 1 Reset: 00 _H	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CC _H	ADC_RCR2 Result Control Register 2 Reset: 00 _H	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CD _H	ADC_RCR3 Result Control Register 3 Reset: 00 _H	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CE _H	ADC_VFCR Valid Flag Clear Register Reset: 00 _H	Bit Field	0				VFC3	VFC2	VFC1	VFC0
		Type	r				w	w	w	w
RMAP = 0, Page 5										

Table 21 System frequency ($f_{\text{sys}} = 80 \text{ MHz}$)

Oscillator	fosc	N	P	K	fsys
On-chip	10 MHz	16	1	2	80 MHz
External	10 MHz	16	1	2	80 MHz
	8 MHz	20	1	2	80 MHz
	5 MHz	32	1	2	80 MHz

Table 22 shows the VCO range for the XC866.

Table 22 VCO Range

f_{VCOmin}	f_{VCOmax}	$f_{\text{VCOFREEmin}}$	$f_{\text{VCOFREEmax}}$	Unit
150	200	20	80	MHz
100	150	10	80	MHz

3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{X1} and C_{X2} , and depending on the crystal type, a series resistor R_{X2} , to limit the current. A test resistor R_Q may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in [Figure 24](#) can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor.

[Figure 24](#) shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.

3.9 Power Saving Modes

The power saving modes of the XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see [Figure 26](#)) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

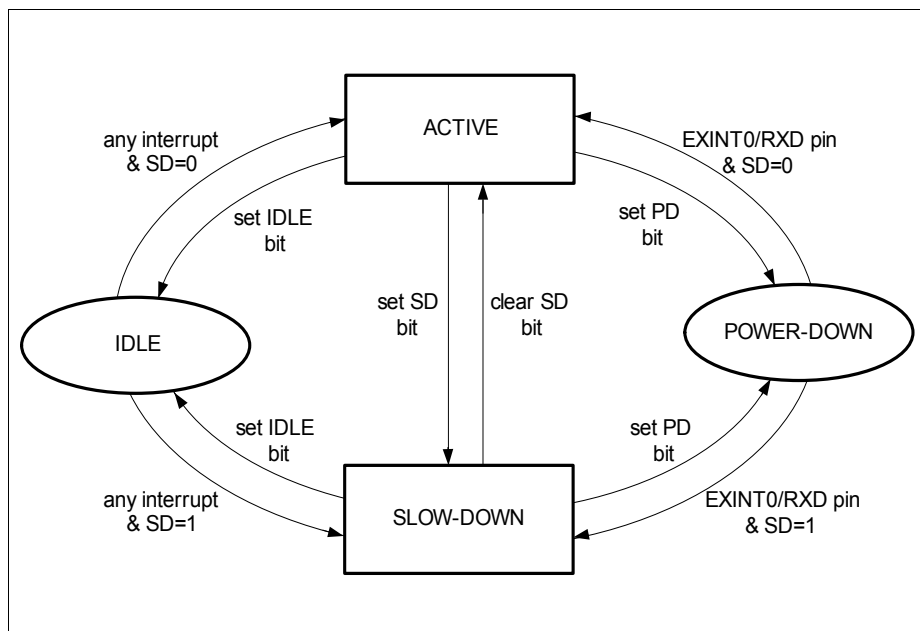


Figure 26 Transition between Power Saving Modes

Functional Description

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert WDTTO) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2⁸). The time period for an overflow of the WDT is programmable in two ways:

- the input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- the reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT} , between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see [Figure 28](#). This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB should not be smaller than WDTREL.

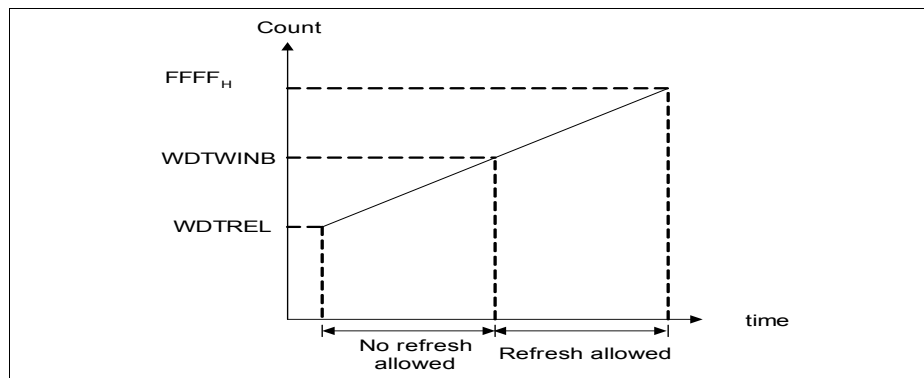


Figure 28 WDT Timing Diagram

3.13 LIN Protocol

The UART can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multiple-slave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in [Figure 30](#). The frame consists of the:

- header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- response time
- data bytes (according to UART protocol)
- checksum

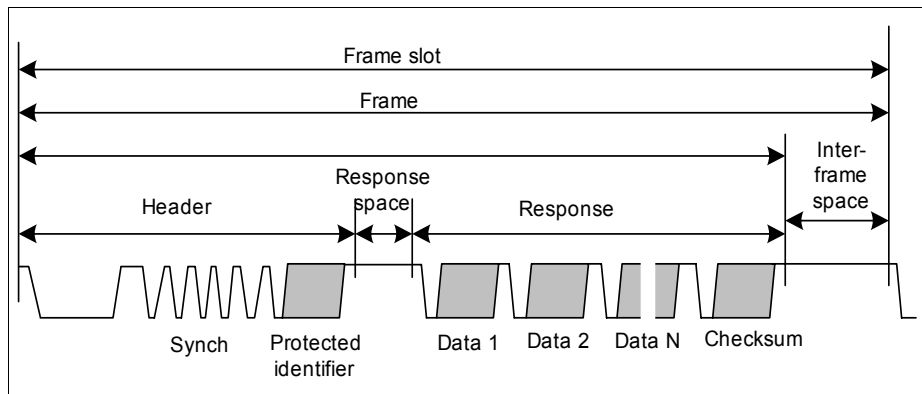


Figure 30 Structure of LIN Frame

3.13.1 LIN Header Transmission

LIN header transmission is only applicable in master mode. In the LIN communication, a master task decides when and which frame is to be transferred on the bus. It also identifies a slave task to provide the data transported by each frame. The information needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data.

Functional Description

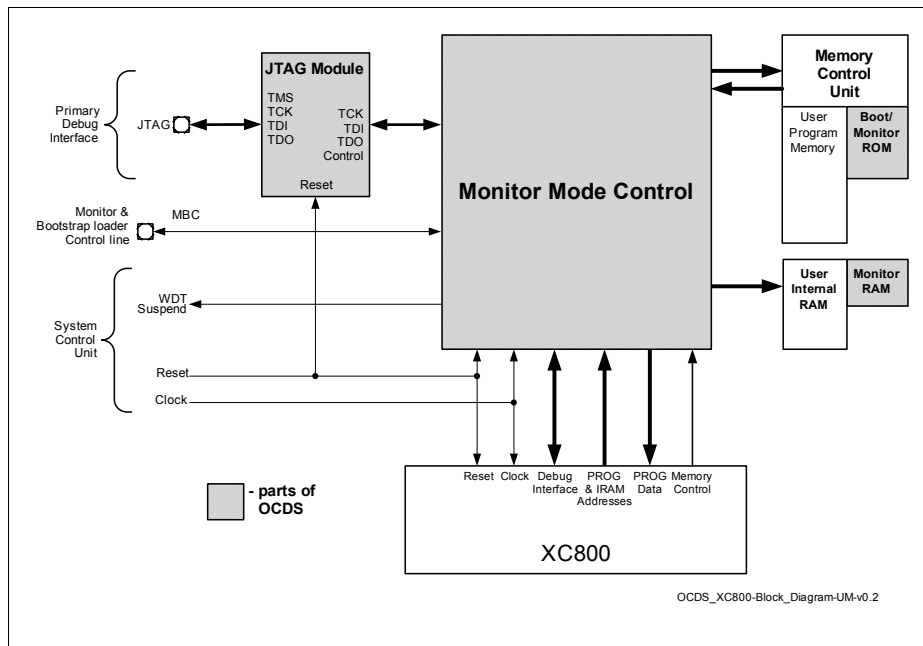


Figure 35 OCDS Block Diagram

3.19.1 JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04_H), and the same is also true immediately after reset.

The JTAG ID register contents for the XC866 devices are given in [Table 31](#).

Table 31 JTAG ID Summary

Device Type	Device Name	JTAG ID
Flash	XC866L-4FR	1010 0083 _H
	XC866-4FR	100F 5083 _H
	XC866L-2FR	1010 2083 _H
	XC866-2FR	1010 1083 _H
	XC866L-1FR	1013 8083 _H
	XC866-1FR	1013 8083 _H

4 Electrical Parameters

Chapter 4 provides the characteristics of the electrical parameters which are implementation-specific for the XC866.

Note: The electrical parameters are valid for the XC866-4FR and XC866-2FR. The electrical parameters for the ROM variants and XC866-1FR are preliminary, differences from XC866-4FR and XC866-2FR are stated explicitly.

4.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in [Section 4.2](#) and [Section 4.3](#).

4.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XC866 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

- **CC**

These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the XC866 and must be regarded for a system design.

- **SR**

These parameters indicate **S**ystem **R**equirements, which must be provided by the microcontroller system in which the XC866 is designed in.

4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the XC866. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 33 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes/ Conditions
		min.	max.		
Digital power supply voltage	V_{DDP}	4.5	5.5	V	5V Device
Digital power supply voltage	V_{DDP}	3.0	3.6	V	3.3V Device
Digital ground voltage	V_{SS}	0		V	
Digital core supply voltage	V_{DDC}	2.3	2.7	V	
System Clock Frequency ¹⁾	f_{SYS}	74	86	MHz	
Ambient temperature	T_A	-40	85	°C	SAF-XC866...
		-40	125	°C	SAK-XC866...

¹⁾ f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is $f_{SYS} / 3$. Please refer to [Figure 25](#) for detailed description.

4.2.2 Supply Threshold Characteristics

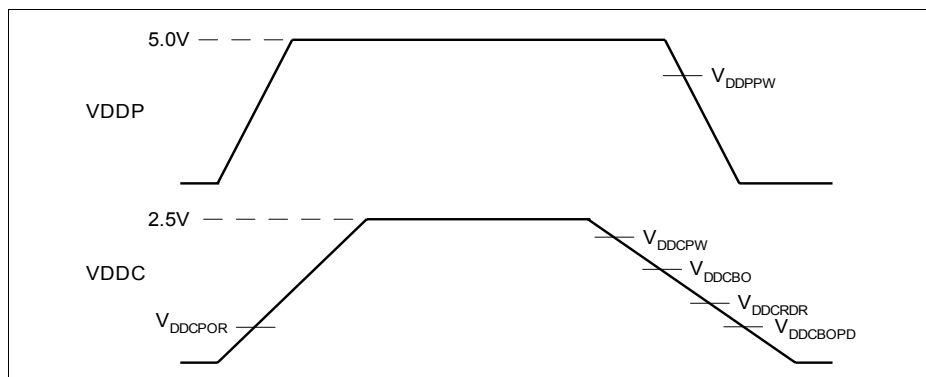


Figure 36 Supply Threshold Parameters

Table 35 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit	Remarks
			min.	typ.	max.		
V_{DDC} prewarning voltage ¹⁾	V_{DDCPW}	CC	2.2	2.3	2.4	V	
V_{DDC} brownout voltage in active mode ¹⁾	V_{DDCBO}	CC	2.0	2.1	2.2	V	XC866-4FR, XC866-2FR
			2.0	2.1	2.3	V	XC866-1FR, ROM device
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V	
V_{DDC} brownout voltage in power-down mode ²⁾	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V	
V_{DDP} prewarning voltage ³⁾	V_{DDPPW}	CC	3.4	4.0	4.6	V	
Power-on reset voltage ²⁾⁴⁾	V_{DDCPOR}	CC	1.3	1.5	1.7	V	

¹⁾ Detection is disabled in power-down mode.

²⁾ Detection is enabled in both active and power-down mode.

³⁾ Detection is enabled for external power supply of 5.0V.
Detection must be disabled for external power supply of 3.3V.

⁴⁾ The reset of EVR is extended by 300 μ s typically after the V_{DDC} reaches the power-on reset voltage.

Electrical Parameters
**Table 39 Power Supply Current Parameters (Operating Conditions apply;
 $V_{DDP} = 3.3V$ range)**

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ. ¹⁾	max. ²⁾		
V_{DDP} = 3.3V Range					
Active Mode	I_{DDP}	21.5	23.3	mA	³⁾
Idle Mode	I_{DDP}	16.4	18.9	mA	XC866-4FR, XC866-2FR ⁴⁾
		11.2	13.5	mA	XC866-1FR, ROM device ⁴⁾
Active Mode with slow-down enabled	I_{DDP}	6.8	8	mA	XC866-4FR, XC866-2FR ⁵⁾
		5.4	7.3	mA	XC866-1FR, ROM device ⁵⁾
Idle Mode with slow-down enabled	I_{DDP}	6.8	7.8	mA	XC866-4FR, XC866-2FR ⁶⁾
		4.9	6.9	mA	XC866-1FR, ROM device ⁶⁾

¹⁾ The typical I_{DDP} values are periodically measured at $T_A = +25\text{ °C}$ and $V_{DDP} = 3.3\text{ V}$.

²⁾ The maximum I_{DDP} values are measured under worst case conditions ($T_A = +125\text{ °C}$ and $V_{DDP} = 3.6\text{ V}$).

³⁾ I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 26.7 MHz (set by on-chip oscillator of 10 MHz and NDIV in PLL_CON to 0010_B), RESET = V_{DDP} , no load on ports.

⁴⁾ I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 26.7 MHz, RESET = V_{DDP} , no load on ports.

⁵⁾ I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 833 KHz by setting CLKREL in CMCON to 0101_B, RESET = V_{DDP} , no load on ports.

⁶⁾ I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enable and running at 833 KHz by setting CLKREL in CMCON to 0101_B, RESET = V_{DDP} , no load on ports.

4.3 AC Parameters

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in [Figure 38](#), [Figure 39](#) and [Figure 40](#).

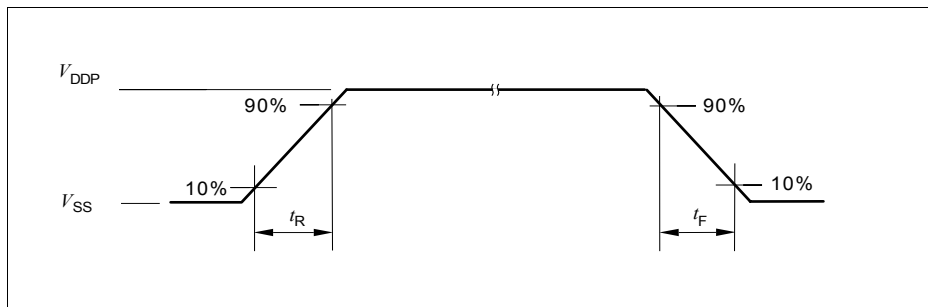


Figure 38 Rise/Fall Time Parameters

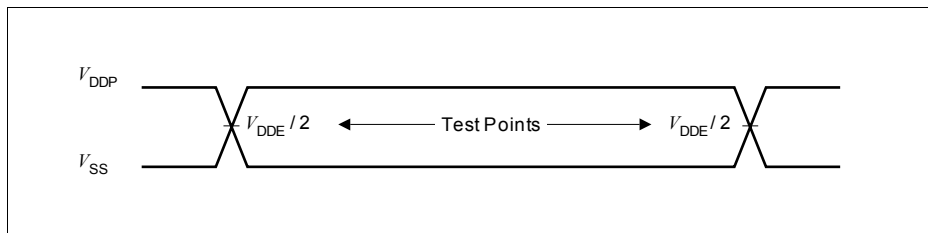


Figure 39 Testing Waveform, Output Delay

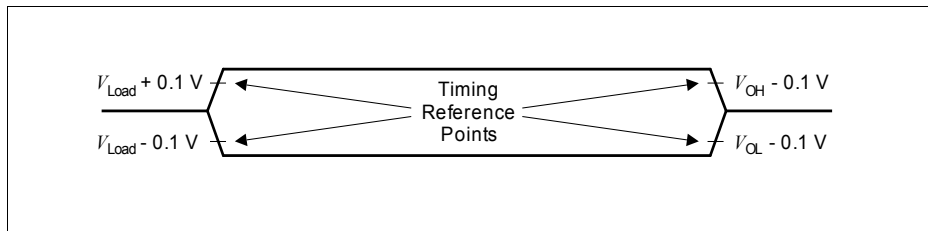


Figure 40 Testing Waveform, Output High Impedance

4.3.3 Power-on Reset and PLL Timing

Table 42 Power-On Reset and PLL Timing (Operating Conditions apply)

Parameter	Symbol	Limit Values			Unit	Test Conditions
		min.	typ.	max.		
Pad operating voltage	V_{PAD} CC	2.3	–	–	V	
On-Chip Oscillator start-up time	t_{OSCST} CC	–	–	500	ns	
Flash initialization time	t_{FINIT} CC	–	160	–	μ s	
$\overline{RESET}$ hold time ¹⁾	t_{RST} SR	–	500	–	μ s	V_{DDP} rise time (10% – 90%) $\leq 500\mu$ s
PLL lock-in in time	t_{LOCK} CC	–	–	200	μ s	
PLL accumulated jitter	D_P	–	–	0.7	ns	²⁾

1) $\overline{RESET}$ signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5V).

2) PLL lock at 80 MHz using a 4 MHz external oscillator. The PLL Divider settings are K = 2, N = 40 and P = 1.

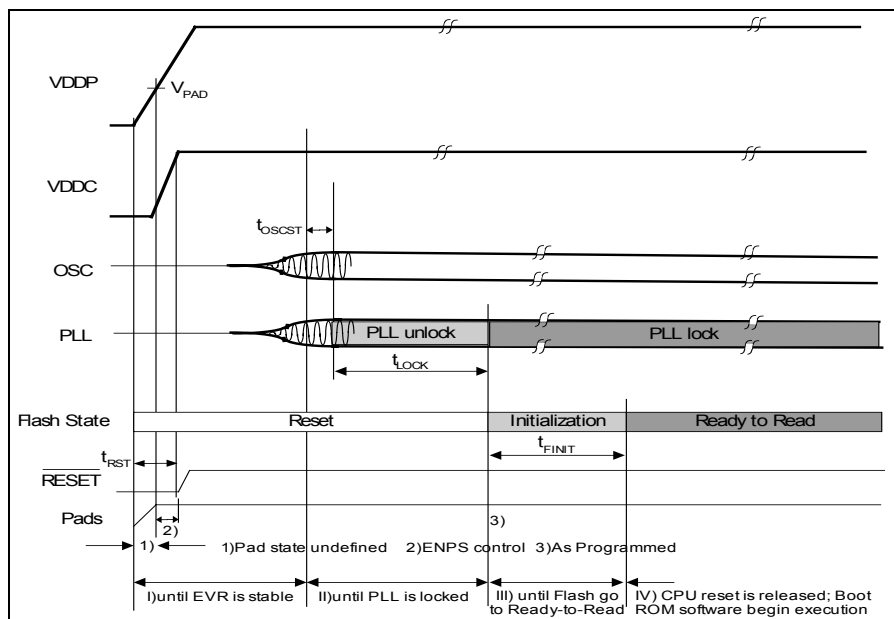
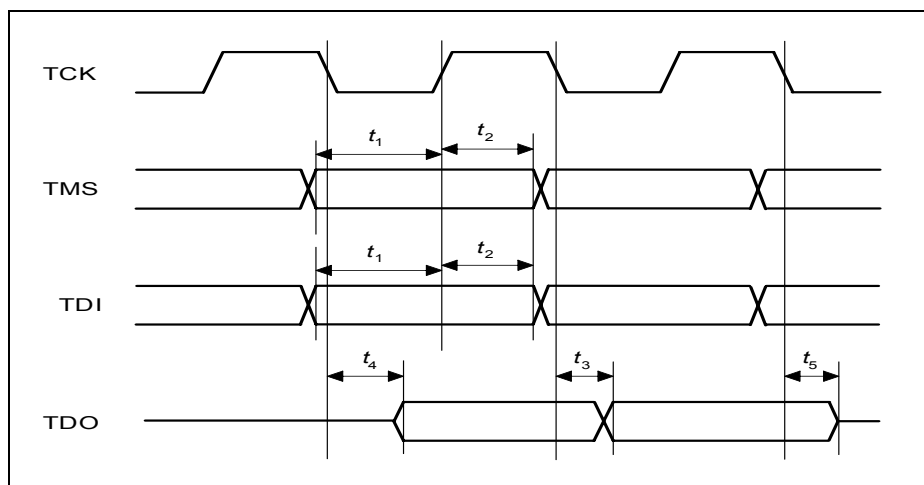


Figure 42 Power-on Reset Timing

Electrical Parameters

Table 45 JTAG Timing (Operating Conditions apply; $C_L = 50$ pF)

Parameter	Symbol		Limits		Unit
			min	max	
TMS setup to TCK 	t_1	SR	8.0	–	ns
TMS hold to TCK 	t_2	SR	5.0	–	ns
TDI setup to TCK 	t_1	SR	11.0	–	ns
TDI hold to TCK 	t_2	SR	6.0	–	ns
TDO valid output from TCK 	t_3	CC	–	23	ns
TDO high impedance to valid output from TCK 	t_4	CC	–	26	ns
TDO valid output to high impedance from TCK 	t_5	CC	–	18	ns


Figure 44 JTAG Timing

5.2 Package Outline

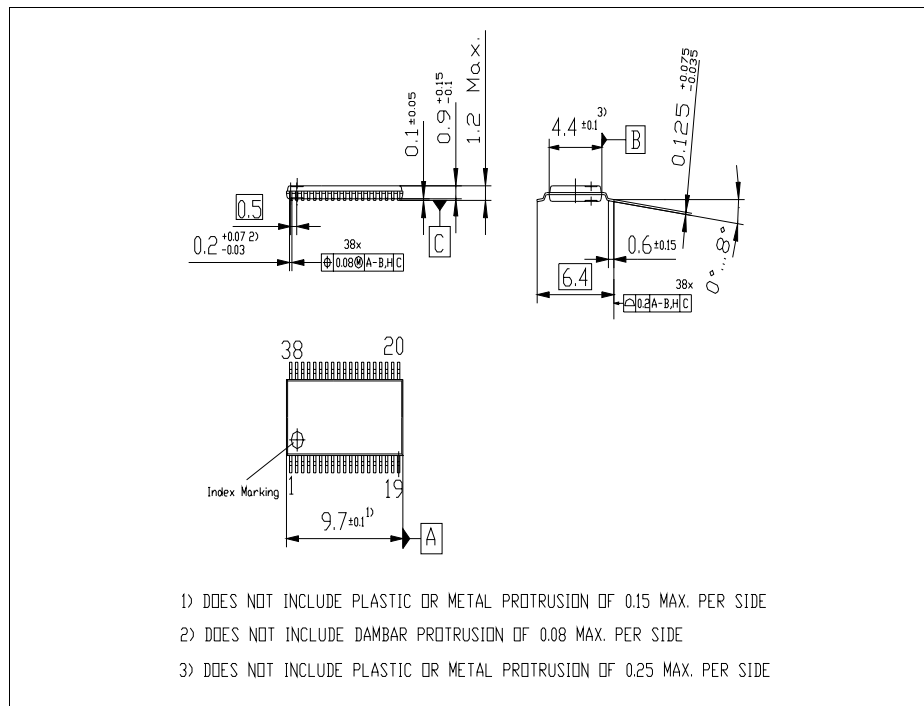


Figure 46 PG-TSSOP-38-4 Package Outline